

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUNHOU ZHENG	06/23/2022
YU CHEN	06/22/2022
SHAOWEI GUO	06/24/2022
YANG BAI	06/24/2022
CHUANYU LI	06/24/2022
WENCHENG LIU	06/24/2022
HAOTIAN KOU	06/24/2022
WEIQI HUANG	06/24/2022
RECEIVING PARTY DATA	
Name:	BEIJING XIAOMI MOBILE SOFTWARE CO., LTD.
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PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	35511303
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ATTORNEY DOCKET NUMBER:	163668.HG003
NAME OF SUBMITTER:	HAO TAN

PATENT

SIGNATURE:	/Hao Tan/
DATE SIGNED:	06/27/2022
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 3 source=Assignment#page1.tif source=Assignment#page2.tif source=Assignment#page3.tif	

COMBINED ASSIGNMENT & DECLARATION

ASSIGNMENT

WHEREAS, Chunhou ZHENG, Yu CHEN, Shaowei GUO, Yang BAI, Chuanyu LI, Wencheng LIU, Haotian KOU and Weiqi HUANG hereinafter called the "Assignors," have made the invention described in the United States design patent application entitled MOBILE PHONE, including but not limited to U.S. Design Application No. 35/511,303, filed January 15, 2021, executed by Assignors on the same date as, or on a date prior to, this Assignment;

WHEREAS, Beijing Xiaomi Mobile Software Co., Ltd., a corporation organized and existing under the laws of P.R. China, having a place of business at No. 018, Floor 8, Building 6, Yard 33, Middle Xierqi Road, Haidian District, Beijing 100085, China, hereinafter called the "Assignee," desires to acquire the entire right, title and interest in and to the invention and the patent application identified above, and all patents which may be obtained for said invention, as set forth below;

NOW, THEREFORE, be it known that, for good and valuable consideration the receipt of which by the Assignors from Assignee is hereby acknowledged, the Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer to the Assignee, the entire right, title and interest for the United States in and to the invention and the patent application identified above, and any patents that may issue for said invention in the United States; together with the entire right, title and interest in and to said invention and all patent applications and patents issuing therefrom in all countries foreign to the United States, including the full right to claim for any such application all benefits and priority rights under any applicable convention; together with the entire right, title and interest in and to all continuations, divisions, reissues, renewals, and extensions of any of the patent applications and patents defined above; together with the right to recover all damages, including, but not limited to, a reasonable royalty, by reason of past, present, or future infringement or any other violation of patent or patent application rights; to have and to hold for the sole and exclusive use and benefit of the Assignee, its successors and assigns, to the full end of the term or terms for all such patents.

The Assignors hereby covenant and agree, for both the Assignors and the Assignors' legal representatives, that the Assignors will assist the Assignee in the prosecution of the patent application identified above; in the making and prosecution of any other patent applications that the Assignee may elect to make covering the invention identified above; in vesting in the Assignee like exclusive title in and to all such other patent applications and patents; and that the Assignors will execute and deliver to the Assignee any and all additional papers which may be requested by the Assignee to carry out the terms of this Assignment.

The Commissioner of Patents and Trademarks is hereby authorized and requested to issue patents to the Assignee in accordance with the terms of this Assignment.

IN TESTIMONY WHEREOF, the Assignors have executed this agreement.

DECLARATION

As the below-named inventor, I hereby declare that:

This Declaration is directed to the attached application. I have reviewed and understand the contents of the above-identified patent application including the claims, and I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-identified patent application. The above-identified patent application was made or authorized to be made by me.

I acknowledge my duty to disclose to the United States Patent and Trademark Office all information that I know to be material to the patentability of this application as defined in 37 C.F.R. § 1.56, including for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby acknowledge that any willful false statement made in this Declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

Further, I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under

18 U.S.C. § 1001 and that such willful false statements may jeopardize the validity of the application and any patent issued thereon.

DATE:	<u>2022年6月23日</u>	Inventor Signature	<u>Chunhou ZHENG</u> Chunhou ZHENG
DATE:	<u>2022年6月22日</u>	Inventor Signature	<u>Yu CHEN</u> Yu CHEN
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Shaowei Guo</u> Shaowei GUO
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Yang Bai</u> Yang BAI
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Chuanyu Li</u> Chuanyu LI
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Liu Wencheng</u> Wencheng LIU
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Haotian Kou</u> Haotian KOU
DATE:	<u>2022年6月24日</u>	Inventor Signature	<u>Weiqi Huang</u> Weiqi HUANG